



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20160118007
Datasheet for DAC121C081, DAC121C085
Information Only**

Date: 2/1/2016
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DAC121C081CIMK/NOPB	null
DAC121C085CIMM/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160118007	PCN Date:	2/1/2016
Title:	Datasheet for DAC121C081/ DAC121C085		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



DAC121C081, DAC121C085

SNAS395E – DECEMBER 2007 – REVISED JANUARY 2016

Changes from Revision D (March 2013) to Revision E

Page

- Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. 1
- Added addresses that the DAC responds to on the I2C bus. 18

The datasheet number will be changing.

Device Family	Change From:	Change To:
DAC121C081, DAC121C085	SNAS395D	SNAS395E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DAC121C081>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DAC121C081CIMK/NOPB	DAC121C081CIMKX/NOPB	DAC121C081CISD/NOPB
DAC121C085CIMM/NOPB	DAC121C085CIMMX/NOPB	DAC121C081CISDX/NOPB

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com